to the frame 24 (which may be part of the housing 22 or module 18 and is not shown in FIG. 8A or 8B). The Braille dot 20, is just a dimple in the top surface 46. Referring now to FIG. 8B, the MEMS microvalve 284a is now closed blocking the flow of pressurized air from the plenum 32 and the MEMS microvalve 284b is now opened allowing the air to evacuate from the chamber 30 to the vent 33. With the pressure vented, the Braille dot 20 contracts, flattening out the dimple on the top surface 46. The voltage to the two the MEMS microvalves 284a, 284b are controlled either directly by the microcontroller 40 or by the module microcontroller 45 to extend and retract Braille dots 20 independent of other Braille dots 20.

FIGS. 9 and 10 show directly actuated devices using is a design for a microelectromechanical device that directly actuates a Braille dot using a thin film shape memory alloy or piezoelectric element to form the Braille dot 20. In FIGS. 9A and 9B, there is shown a detailed view of a Braille dot 24) and MEMS device 16 which uses either a thin film shape 20 memory alloy or piezoelectric element 282 as the actuator. A thin film SMA based microelectromechanical actuator is significantly different than traditional bulk shape memory alloy actuators in size, fabrication techniques, and operation. The mechanical properties of a thin film SMA can be 25 precisely tailored by changing the alloy ratios during fabrication while a macro sized bulk SMA actuator may have regions where the alloy ratio changes within the bulk material of the actuator, these regions will increase power film SMA actuators have greater fatigue life and improved phase transition characteristics then traditional bulk SMA actuators. The thin film SMA also has faster response and lower power consumption than traditional bulk SMA actuawhich allows the actuator to change from one phase state to another faster than the larger bulk SMA actuators. The rapid response of the thin-film SMA actuators allows a user to quickly scroll through a document without having the refresumption of a thin film SMA actuator reduces the amount of heat that needs to be dissipated from the actuators during operation and can permit battery operation for use with portable electronic devices. Shape Memory Alloys (SMA's) two different crystalline phases, defined as martensite and austenite, in response to temperature and strain. SMA's are produced by equiatomically combining at least two component metals into a desired shape, which is then annealed. a certain shape and characterized by low ductility, high Young's modulus and high yield stress. Upon cooling the SMA changes to the martensite phase characterized by high ductility, a low Young's modulus and low yield stress. In the martensite phase, the SMA is easily deformed and can take 55 on a different shape from its austenite or original shape by applying an external strain. The SMA will retain this different shape until it is heated to its austenitic transformation temperature. When the SMA is heated to its austenitic transformation temperature the SMA transitions to its austenite phase and transforms back to its original shape. Similarly, piezoelectric elements 282 can be tailored for the application. FIGS. 9A and 9B also show the application of a direct actuation of the Braille dot 20 without the need of a pneumatic or hydraulic force.

If a thin film SMA element 282 is used then in FIG. 9A the thin film SMA element 282 is in its martensite phase with

the Braille dot 20 retracted. Since the martensite phase is characterized by high ductility, low Young's modulus and low yield stress, the thin film SMA element 282 is easily deformed by external stresses like biasing means 283, shown as a spring in FIG. 10. When heated to its austenitic transfer temperature, the thin film SMA element 282 transitions from its martensite phase to its austenite phase transforming to its austenitic or original shape. The force produced by the biasing means 283 is less than the force produced by the thin film SMA element 282 during this transformation. The thin film SMA element 282, thereby, overcomes that force during this transformation, and, in so doing, extends the Braille dot 20 as shown in FIG. 9B. The thin film SMA element 282 is heated by joule heating using shape memory alloy or piezoelectric based devices. FIG. 9 15 electric current from an electric power source controlled by the microcontroller 40 (not shown in FIG. 9A or 9B). Because the austenite phase is characterized by low ductility, high Young's modulus and high yield stress, the thin film SMA element 282 remains in its austenitic or original shape and the Braille dot 20 remains extended. When the electric current is removed, the thin film SMA element 282 cools to its martensitic transfer temperature at which point it transitions to the martensite phase and the external stress from the biasing means 283 deforms the thin film SMA element 282, retracting the Braille dot 20. Alternately, the thin film SMA element 282 can be operably connected to the Braille dot 20 to retract it when transitioning from its martensite phase to its austenite phase. The Braille dot 20, then, will be extended by the biasing means 283, when the thin film SMA element consumption, reduce fatigue resistance and limit life. Thin 30 282 transitions from the austenite phase to the martensite phase. The Braille dot 20 is extended and retracted based upon the crystalline phase of the thin film SMA element 282. Instead of a spring as shown, the biasing means 283 can be any mechanism including a second thin film SMA element, tors due to their reduced volume and large surface area 35 a diaphragm or manipulated boss. Again, similarly a piezoelectric element 282 can be used so when a electric field is applied the thin film expands resulting in a similar movement of the element 282.

In FIGS. 10A and 10B, the thin film SMA or piezoelectric shable Braille display lag behind. The lower power con- 40 element is shown directly forming the Braille dot itself 282. The Braille dot may be covered with a polymer cover 20 which can provide a biasing force to flatten the Braille dot. The biasing force may be provided by either a pressure or a vacuum applied through the orifice located directly under are a unique class of alloys which have the ability to form 45 the SMA film 282. Similarly direct actuation of the Braille dot 20 can be accomplished with a MEMS device 16 utilizing other mechanisms not based on shape memory alloy like springs, diaphragms and bosses. It is only necessary to have opposite biasing forces operably attached to the When produced, the SMA is in the austenite phase, having 50 Braille dot 20 in a manner such that the Braille dot 20 can be extended and retracted in response to signals from the microcontroller 40 or module microcontrollers 45.

> In another embodiment shown in FIG. 11, the present invention includes an electrostatic microelectromechanical valve having a structure with an open and a closed position comprising an inlet port 301; a base plate 302 containing an electrode 303; and a closure diaphragm 304 containing an electrode 305 wherein the diaphragm 304 with a boss 306 for closing the inlet port 301 and at least two radial beams 307 to connect the boss 306 to the main microelectromechanical valve structure. FIG. 11A shows an open valve. FIG. 11B shows a closed valve and FIG. 11C shows the diaphragm from above. Preferably, the boss of the diaphragm is connected to the main microelectromechanical valve structure by at least four beams 307, and more preferably by at least eight beams 307. In FIGS. 12 A, B, C, D, E, F, G, and H, various electrostatic microelectrome-